

Figure 1: Printing and Plating. Typical schematic procedure for making stamp from photoresist master pattern, inking with thiol, stamping thiol on gold to form SAM protective pattern, etching away unprotected gold, electroless plating of copper

lines on top of remaining gold.

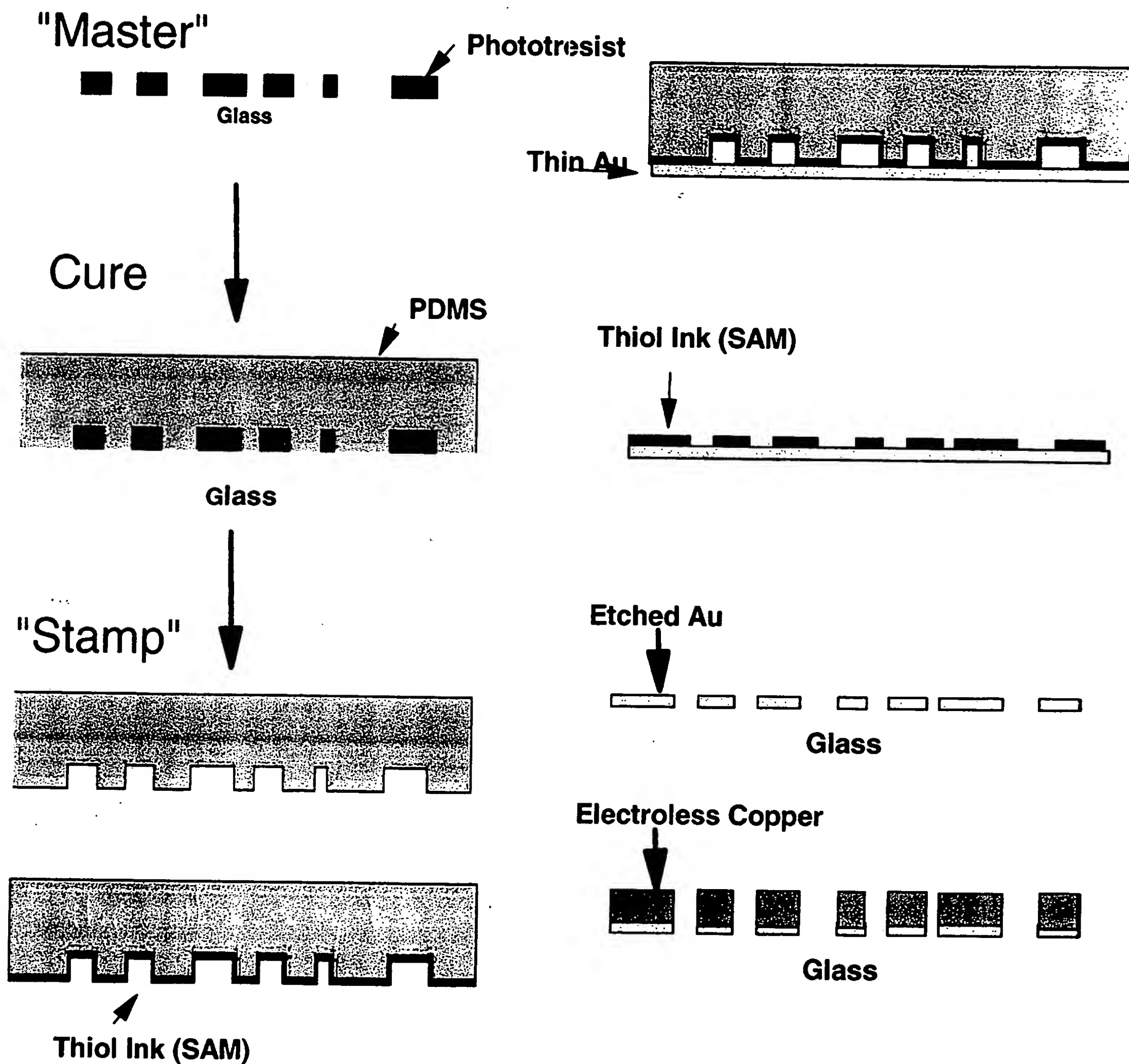


Figure 2: Standard one-step curing me

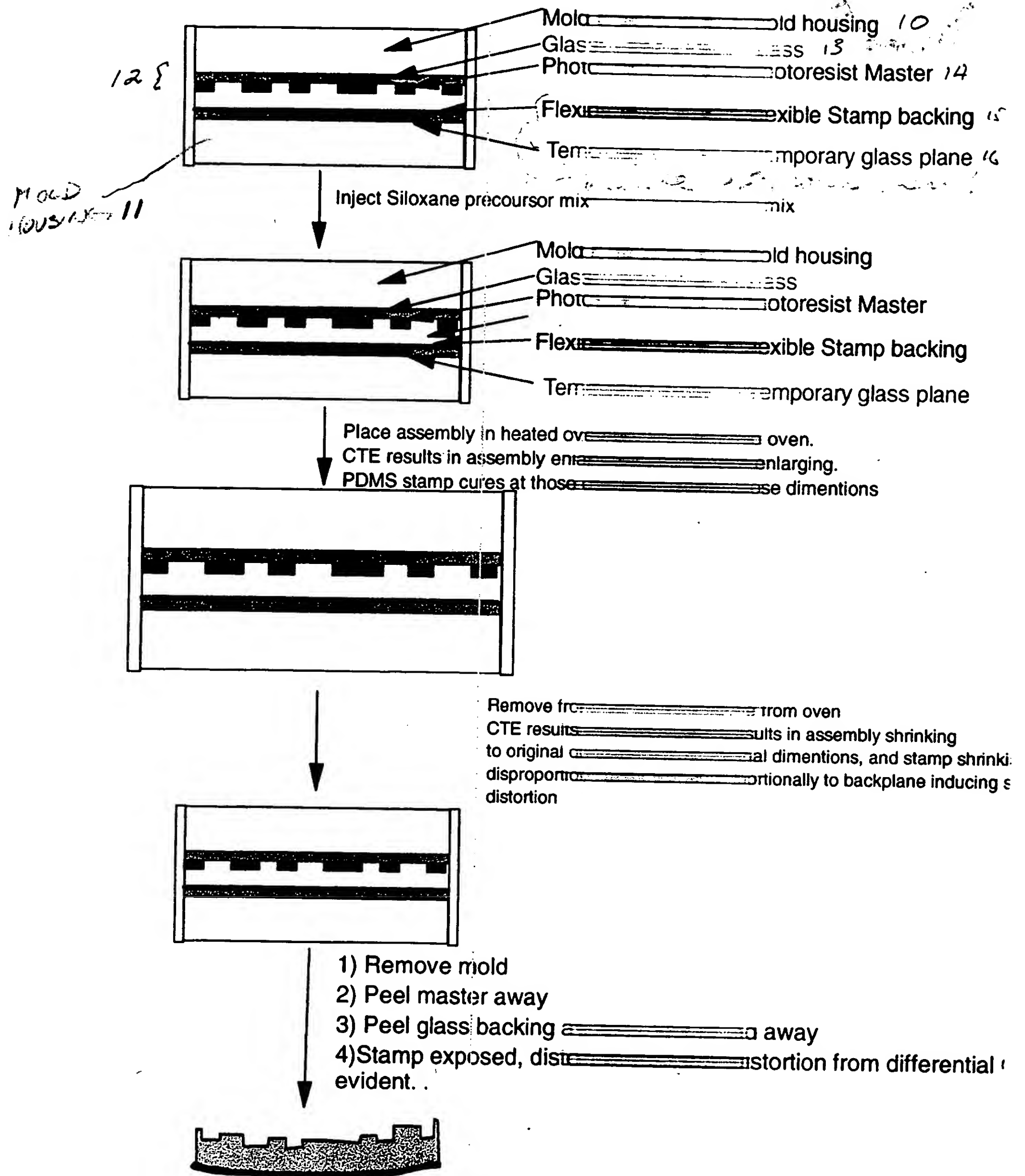


Figure 3: Two stage curing of siloxane stamp.

